Attorney Docket No.: 18865-007400US

Carrier with Metal Bumps for Semiconductor Die Packages

ABSTRACT OF THE DISCLOSURE

A carrier for a semiconductor die package is disclosed. In one embodiment, the carrier includes a metal layer and a plurality of bumps formed in the metal layer. The bumps can be formed by stamping.

SF 1216452 v1

10

on's show young grant should alone the back that the should be the shoul

Maria Arrika, 33. septem arrana gawa, 343. H. H. H. Sappelli, G. Staria, G. H. H. Samir, H. S. W. court strate

5